



3.3V PCI Express® 3.0 2-Lane Exchange Switch

Features

- → 8 Differential Channel (2-lane) Exchange
- → PCI Express[®] 3.0 performance, 8.0 Gbps
- → Bi-directional operation
- \rightarrow Low Bit-to-Bit Skew: 10ps (between \pm signals)
- → Low Crosstalk: -29dB @ 2.5GHz (5Gbps) -20dB @ 4.0GHz (8Gbps)
- → Low Insertion Loss: -1.1dB @ 2.5GHz (5Gbps) -1.45dB @ 4.0GHz (8Gbps)
- → V_{DD} Operating Range: 3.3V ±10%
- → Industrial Temperature Range: -40°C to 85°C
- → ESD Tolerance: 2kV HBM
- → Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- → Halogen and Antimony Free. "Green" Device (Note 3)
- → Packaging (Pb-free & Green):
 - ^a 42-contact, TQFN (ZH42), 3.5x9mm.
 - □ 40-contact, TQFN (ZL40), 3x6mm.

Application

Switching 4 lanes of DP1.2 from PC/Notebook/Tablet to Display monitor

Truth Table

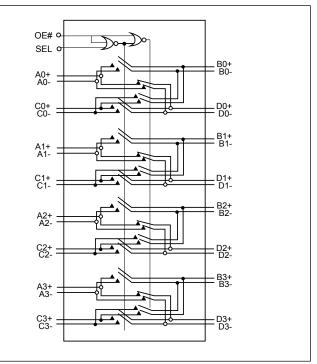
| Function | SEL | OE# |
|------------------------------------|-----|-----|
| Ax = Bx $Cx = Dx$ | 0 | 0 |
| Ax = Dx $Cx = Bx$ | 1 | 0 |
| Ax, Bx, Cx, Dx = Hi-Z (disconnect) | х | 1 |

Description

Diodes' PI3PCIE3442A is a differential exchange switch featuring pass-through pinout. It supports two full PCI Express® lanes operating at 8.0Gbps PCIe[®] 3.0 performance.

With the select control input low, Port A connects to Port B, and Port C connects to port D for an 8-channel differential passthough. When the select control input is high Port A connects to Port D, and Port B connects to Port C.

Block Diagram



Notes:

^{1.} No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

^{2.} See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm

antimony compounds.

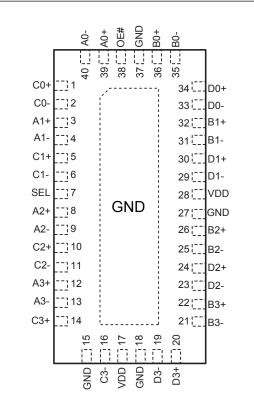




Pin Diagram 42-TQFN

| | | 2 | |
|--------------------|-------------------|-----|-----|
| | VDD OE# VDD | | |
| A0+1 | 42! 41! 39 | 38 | B0+ |
| A0 | ч ч ч « | 37! | B0- |
| C0+ <u></u> 13 | | 36¦ | D0+ |
| C0- <u></u>]4 | | 35¦ | D0- |
| A1+15 | | 34¦ | B1+ |
| A16 | | 33¦ | B1- |
| C1+ <u></u> 17 | | 32¦ | D1+ |
| C1 | GND | 31¦ | D1- |
| SEL <u></u> 19 | GND | 30¦ | VDD |
| A2+ 10 | | 29¦ | B2+ |
| A2- | | 28¦ | B2- |
| C2+ <u></u> 12 | | 27¦ | D2+ |
| C213 | | 26¦ | D2- |
| A3+14 | | 25¦ | B3+ |
| A3115 | | 24¦ | B3- |
| C3+ <u></u> 16 | | 23¦ | D3+ |
| C317 | | 22; | D3- |
| | | | |
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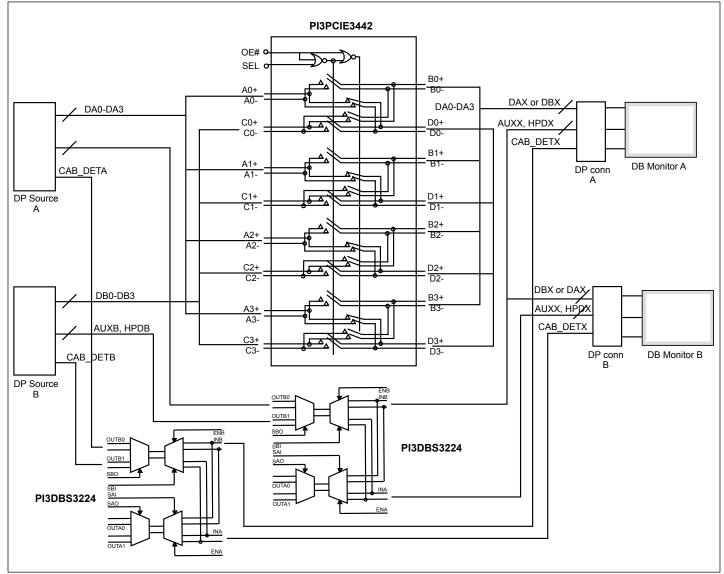
Pin Diagram 40-TQFN







Application Diagram



Generic 2 x 2 DP1.2 Switching Using PI3PCIE3442A (3x6mm 40 pad QFN)





Pin Description (42-TQFN)

| Pin # | Pin Name | I/O | Description |
|------------------------|-----------------|-----|--|
| 1 | A0+ | I/O | Signal I/O, Channel 0, Port A |
| 2 | A0- | | |
| 5 | A1+ | I/O | Signal I/O, Channel 1, Port A |
| 6 | A1- | | |
| 10 | A2+ | I/O | Signal I/O, Channel 2, Port A |
| 11 | A2- | | |
| 14 | A3+ | I/O | Signal I/O, Channel 3, Port A |
| 15 | A3- | | |
| 38 | B0+ | I/O | Signal I/O, Channel 0, Port B |
| 37 | B0- | | |
| 34 | B1+ | I/O | Signal I/O, Channel 1, Port B |
| 33 | B1- | | |
| 29 | B2+ | I/O | Signal I/O, Channel 2, Port B |
| 28 | B2- | | |
| 25 | B3+ | I/O | Signal I/O, Channel 3, Port B |
| 24 | B3- | | |
| 3 | C0+ | I/O | Signal I/O, Channel 0, Port C |
| 4 | C0- | | |
| 7 | C1+ | I/O | Signal I/O, Channel 1, Port C |
| 8 | C1- | | |
| 12 | C2+ | I/O | Signal I/O, Channel 2, Port C |
| 13 | C2- | | |
| 16 | C3+ | I/O | Signal I/O, Channel 3, Port C |
| 17 | С3- | | |
| 36 | D0+ | I/O | Signal I/O, Channel 0, Port D |
| 35 | D0- | | |
| 32 | D1+ | I/O | Signal I/O, Channel 1, Port D |
| 31 | D1- | | |
| 27 | D2+ | I/O | Signal I/O, Channel 2, Port D |
| 26 | D2- | | |
| 23 | D3+ | I/O | Signal I/O, Channel 3, Port D |
| 22 | D3- | | |
| 41 | OE# | Ι | Output Enable, active low. When OE# = 0 the device I/O is enabled. When OE#=1, all I/O are high impedance |
| 9 | SEL | Ι | Operation mode Select (when SEL=0: $A \rightarrow B$, $C \rightarrow D$, when SEL=1: $A \rightarrow D$, $C \rightarrow B$) |
| 18, 20, 30, 40, 42 | V _{DD} | Pwr | 3.3V ±10% Positive Supply Voltage |
| 19, 21, 39, Center Pad | GND | Pwr | Power ground |





Pin Description (40-TQFN)

| Pin # | Pin Name | I/O | Description |
|----------------------------|-----------------|-----|--|
| 39 | A0+ | I/O | Signal I/O, Channel 0, Port A |
| 40 | A0- | | |
| 3 | A1+ | I/O | Signal I/O, Channel 1, Port A |
| 4 | A1- | | |
| 8 | A2+ | I/O | Signal I/O, Channel 2, Port A |
| 9 | A2- | | |
| 12 | A3+ | I/O | Signal I/O, Channel 3, Port A |
| 13 | A3- | | |
| 36 | B0+ | I/O | Signal I/O, Channel 0, Port B |
| 35 | B0- | | |
| 32 | B1+ | I/O | Signal I/O, Channel 1, Port B |
| 31 | B1- | | |
| 26 | B2+ | I/O | Signal I/O, Channel 2, Port B |
| 25 | B2- | | |
| 22 | B3+ | I/O | Signal I/O, Channel 3, Port B |
| 21 | B3- | | |
| 1 | C0+ | I/O | Signal I/O, Channel 0, Port C |
| 2 | C0- | | |
| 5 | C1+ | I/O | Signal I/O, Channel 1, Port C |
| 6 | C1- | | |
| 10 | C2+ | I/O | Signal I/O, Channel 2, Port C |
| 11 | C2- | | |
| 14 | C3+ | I/O | Signal I/O, Channel 3, Port C |
| 16 | C3- | | |
| 34 | D0+ | I/O | Signal I/O, Channel 0, Port D |
| 33 | D0- | | |
| 30 | D1+ | I/O | Signal I/O, Channel 1, Port D |
| 29 | D1- | | |
| 24 | D2+ | I/O | Signal I/O, Channel 2, Port D |
| 23 | D2- | | |
| 20 | D3+ | I/O | Signal I/O, Channel 3, Port D |
| 19 | D3- | | |
| 38 | OE# | Ι | Output Enable, active low. When OE# = 0 the device I/O is enabled. When OE#=1, all I/O are high impedance |
| 7 | SEL | Ι | Operation mode Select (when SEL=0: $A \rightarrow B$, $C \rightarrow D$, when SEL=1: $A \rightarrow D$, $C \rightarrow B$) |
| 17, 28 | V _{DD} | Pwr | 3.3V ±10% Positive Supply Voltage |
| 15, 18, 27, 37, Center Pad | GND | Pwr | Power ground |





Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

| Storage Temperature | 65°C to +150°C |
|------------------------------------|-------------------------|
| Supply Voltage to Ground Potential | -0.5V to +3.7V |
| DC Input Voltage | 0.5V to V _{DD} |
| DC Output Current | 120mA |
| Power Dissipation | 0.5W |
| Junction Temperature | 125°C |
| | |

Note: Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics Recommended Operating Conditions

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Units |
|-----------------|---|---------------------------------------|------|------|------|-------|
| V _{DD} | 3.3V Power Supply | | 3.0 | 3.3 | 3.6 | V |
| I _{DD} | Total current from V _{DD} 3.3V supply | SEL and OE# at OV or $\rm V_{\rm DD}$ | | | 300 | μΑ |
| T _A | Operating temperature range | | -40 | | 85 | °C |

DC Electrical Characteristics for Switching over Operating Range

| Parameters | Description | Test Conditions ⁽¹⁾ | Min. | Typ. ⁽¹⁾ | Max. | Units |
|-----------------|--|---|--|---------------------|---------------------------|-------|
| V _{IH} | Input HIGH Voltage | Guaranteed HIGH level | $0.65 \mathrm{x} \mathrm{V}_\mathrm{DD}$ | | | |
| V _{IL} | Input LOW Voltage | Guaranteed LOW level | -0.5 | | $0.35 \mathrm{~x~V_{DD}}$ | V |
| V _{IK} | Clamp Diode Voltage | $V_{DD} = Max., I_{IN} = -18mA$ | | -0.7 | -1.2 | |
| I _{IH} | Input HIGH Current, SEL | $V_{DD} = Max., V_{IN} = V_{DD}$ | -10 | | +10 | |
| I _{IL} | Input LOW Current, SEL | V _{DD} = Max., V _{IN} = GND | -10 | | +10 | μΑ |
| IIH | Input HIGH Current, A_X , B_X , C_{X_1} D_X | $V_{DD} = Max., V_{IN} = 1.8V$ | -10 | | +10 | μA |
| IIL | Input LOW Current, A _X , B _X , C _X , D _X | $V_{DD} = Max., V_{IN} = 0V$ | -10 | | +10 | F |

Note:

1. Typical values are at VDD = 3.3V, TA = 25°C ambient and maximum loading.

Switching Characteristics

| Parameters | Description | Test Conditions | Min. | Тур. | Max. | Units |
|-------------------------------------|--|-----------------|------|------|------|-------|
| t _{PZH} , t _{PZL} | Line Enable Time - SEL to A_N , B_N , C_N , D_N | | 0.5 | | 45 | |
| t _{PHZ} , t _{PLZ} | Line Disable Time - SEL to A_N , B_N , C_N , D_N | | 0.5 | | 25 | ns |
| t _{b-b} | Bit-to-bit skew within the same differential pair 10 | | 10 | | | |
| t _{ch-ch} | Channel-to-channel skew | | | | 20 | ps |





Dynamic Electrical Characteristics

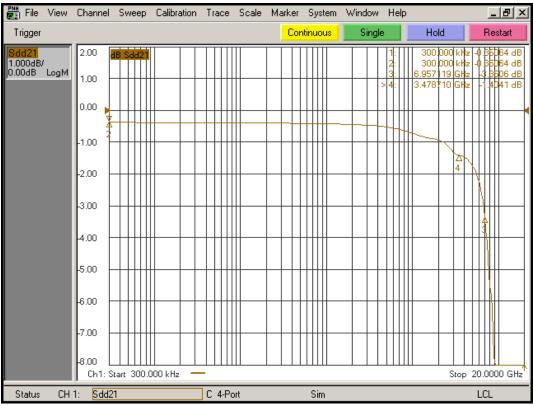
| Parameter | Description | Test Conditions | Min. | Typ. ⁽¹⁾ | Max. | Units |
|-----------|---|---|------|---------------------|------|-------|
| | | f=1.2GHz | | -0.8 | -1.0 | |
| | D:fferential Incention I and | f=2.5GHz | | -1.0 | -1.2 | |
| DDIL | Differential Insertion Loss | f=4.0GHz | | -1.3 | -1.9 | dB |
| | $(V_{\rm IN} = -10 dBm, DC = 0V)$ | f=5.0GHz | | -1.8 | -2.6 | |
| | | f=7.5GHz | | -4.5 | -5.6 | |
| DDIL | Differential Off Isolation | f= 4.0GHz | | -19 | | dB |
| | | f= 0 to 2.8GHz | | -26 | | |
| DDRL | Differential Return Loss | f= 2.8 to 5.0GHz | | -14 | | dB |
| | | f= 5.0 to 8.0GHz | | -7.5 | | |
| | | f= 0 to 2.8GHz | | -26 | | |
| DDNEXT | Near End Crosstalk | f= 2.8 to 5.0GHz | | -20 | | dB |
| | | f= 5.0 to 8.0GHz | | -16 | | |
| | | Insertion loss 1.5dB, V _{IN} =0.623Vpp, DC=0V | | 4.0 | | |
| 17 | V _{I F} Max Signal Frequency Range | Insertion loss 1.5dB, V _{IN} =0.623Vpp, DC=0.9V | | 4.0 | | |
| VIF IVI | | Insertion loss 3dB, V _{IN} =0.623Vpp, DC=0V | | 8.0 | | GHz |
| | | Insertion loss 3dB, V _{IN} =0.623Vpp, DC=0.9V | | 8.0 | | |
| BW | -3dB Bandwidth | | | 6.5 | | GHz |

Notes:

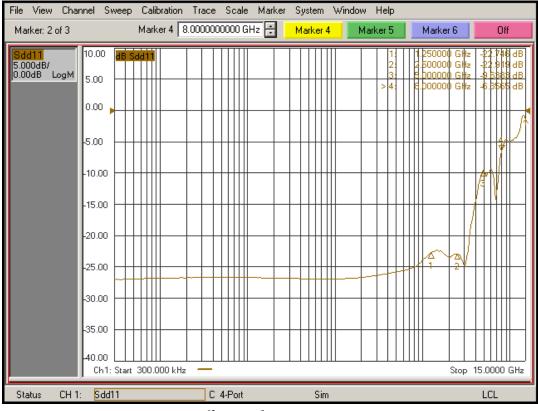
1. Guaranteed by design. Typical values are at $\rm V_{DD}$ = 3.3V , $\rm T_A$ = 25°C ambient and maximum loading.







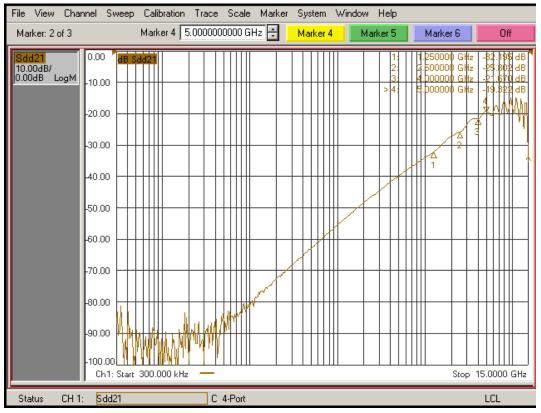
Differential Insertion Loss



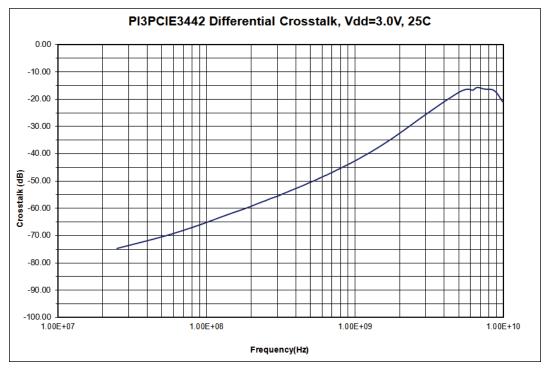
Differential Return Loss







Differential Off Isolation

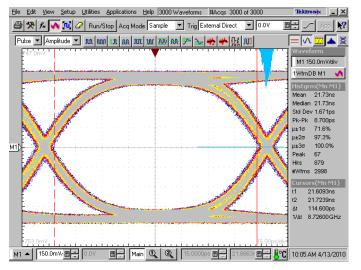


Differential Crosstalk

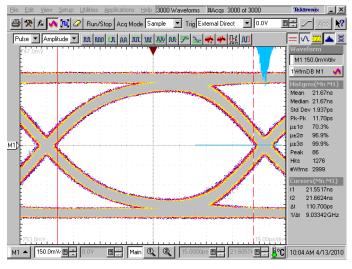


A product Line of Diodes Incorporated

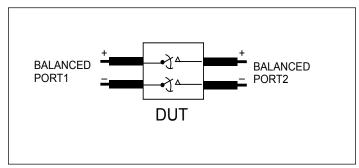
PI3PCIE3442A



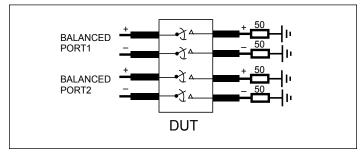
8.0 Gbps RX signal eye without PI3PCIE3442A



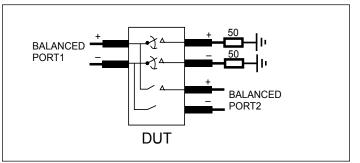
8.0 Gbps RX signal eye with PI3PCIE3442A



Differential Insertion Loss and Return Test Circuit



Differential Near End Xtalk Test Circuit

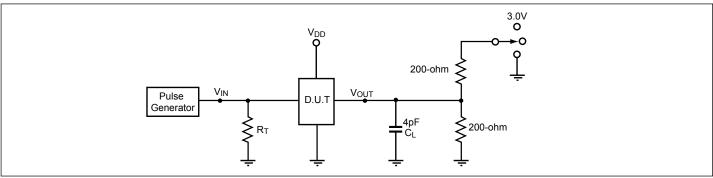


Differential Off Isolation Test Circuit





Test Circuit for Electrical Characteristics⁽¹⁻⁵⁾



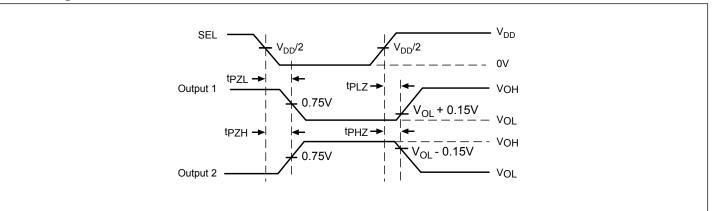
Notes:

- 1. C_L = Load capacitance: includes jig and probe capacitance.
- 2. R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator
- 3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. All input impulses are supplied by generators having the following characteristics: PRR \leq MHz, $Z_{O} = 50\Omega$, $t_{R} \leq 2.5$ ns, $t_{F} \leq 2.5$ ns.
- 5. The outputs are measured one at a time with one transition per measurement.

Switch Positions

| Test | Switch |
|-------------------------------------|--------|
| t_{PLZ}, t_{PZL} | 3.0V |
| t _{PHZ} , t _{PZH} | GND |
| Prop Delay | Open |

Switching Waveforms

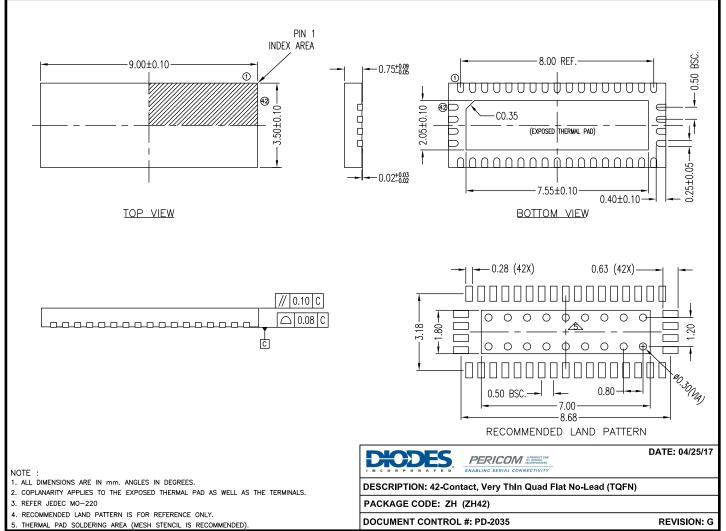


Voltage Waveforms Enable and Disable Times





Packaging Mechanical: 42-TQFN (3.5x9mm) (ZH)

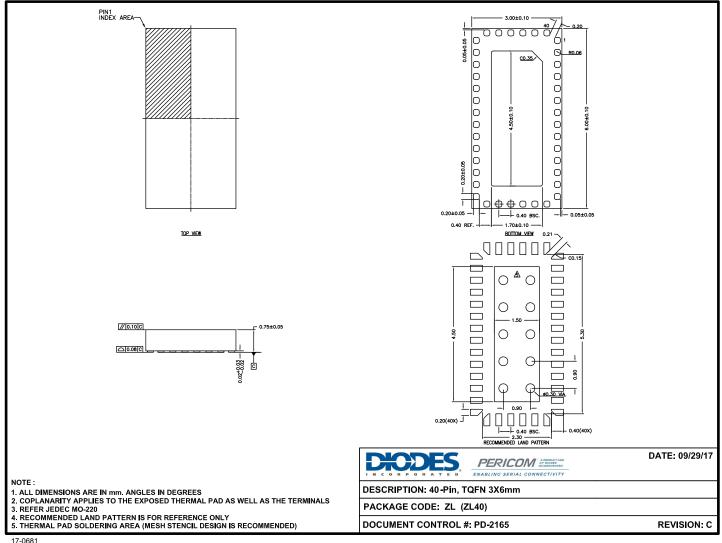


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Packaging Mechanical: 40-TQFN (3x6mm) (ZL)



For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

| Ordering Code | Package Code | Package Description |
|------------------|--------------|--|
| PI3PCIE3442AZHEX | ZH | 42-Contact, Very Thin Quad Flat No-Lead (TQFN) |
| PI3PCIE3442AZLEX | ZL | 40-Contact, 3 x 6mm (TQFN) |

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. E = Pb-free and Green

5. X suffix = Tape/Reel





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